

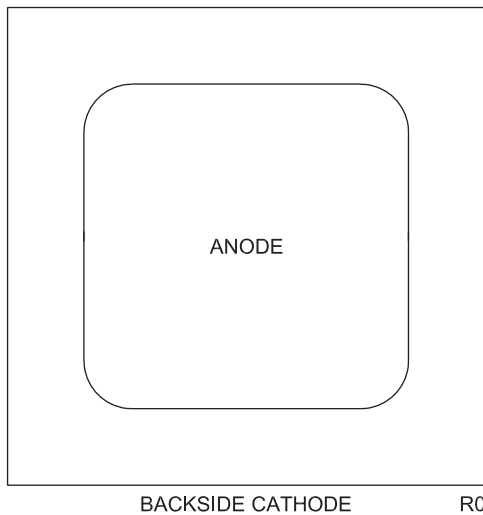
**PROCESS CPD05**  
**General Purpose Rectifier**  
1 Amp Glass Passivated Rectifier Chip



**PROCESS DETAILS**

Process	GLASS PASSIVATED MESA
Die Size	51 x 51 MILS
Die Thickness	10.2 MILS
Anode Bonding Pad Area	36 x 36 MILS
Top Side Metalization	Ni/Au - 5,000Å/2,000Å
Back Side Metalization	Ni/Au - 5,000Å/2,000Å

**GEOMETRY**



**GROSS DIE PER 4 INCH WAFER**

4,250

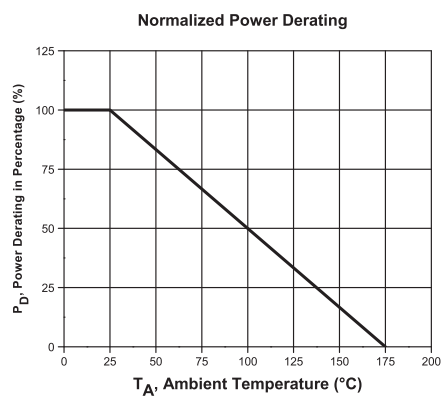
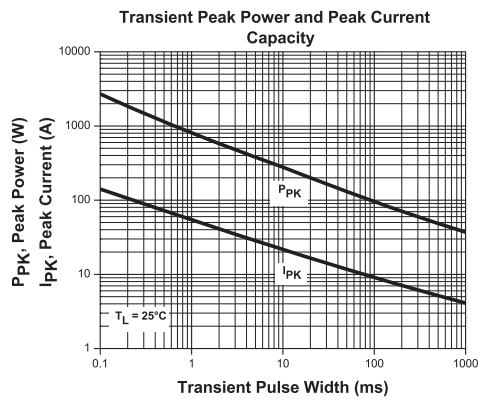
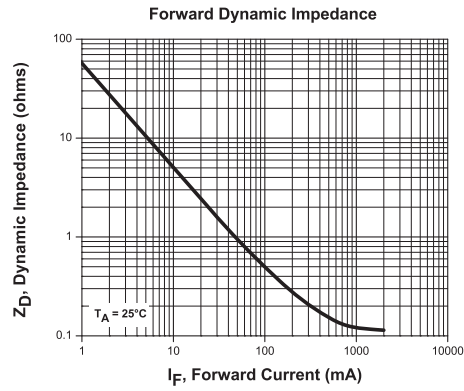
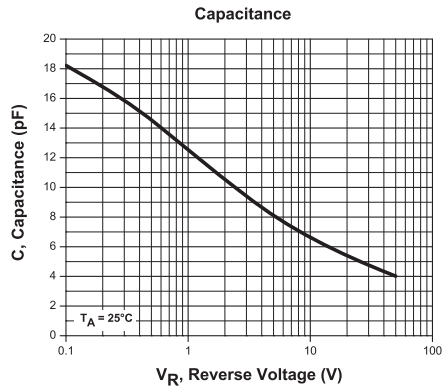
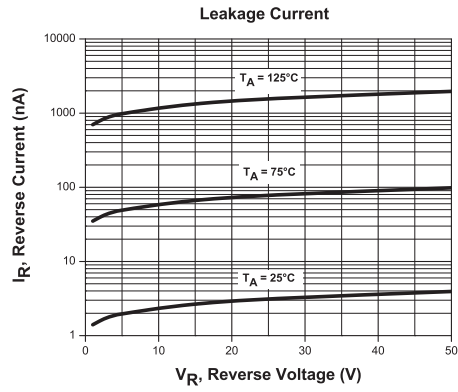
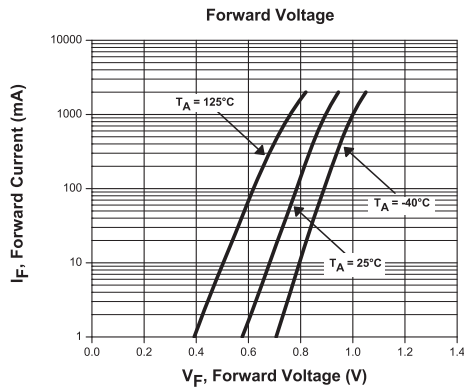
**PRINCIPAL DEVICE TYPES**

1N3611 thru 1N3614  
1N4001 thru 1N4007  
1N4245 thru 1N4249  
1N5059 thru 1N5062  
1N5391 thru 1N5399  
1N5614 thru 1N5622  
CMR1-02 Series  
CMR1-02M Series

R4 (22-March 2010)

# PROCESS CPD05

## Typical Electrical Characteristics



R4 (22-March 2010)

## BARE DIE PACKING OPTIONS

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### BARE DIE IN TRAY (WAFFLE) PACK

**CT:** Singulated die in tray (waffle) pack.  
(example: CP211-PART NUMBER-CT)

**CM:** Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).  
(example: CP211-PART NUMBER-CM)

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### UNSAWN WAFER

**WN:** Full wafer, unsawn, 100% tested with reject die inked.  
(example: CP211-PART NUMBER-WN)

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### SAWN WAFER ON PLASTIC RING

**WR:** Full wafer, sawn and mounted on plastic ring,  
100% tested with reject die inked.  
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:  
[www.centrasemi.com/bdspecs](http://www.centrasemi.com/bdspecs)

## OUTSTANDING SUPPORT AND SUPERIOR SERVICES



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### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

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### DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

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### REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix " TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

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### CONTACT US

#### Corporate Headquarters & Customer Support Team

Central Semiconductor Corp.  
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Hauppauge, NY 11788 USA  
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Main Fax: (631) 435-1824  
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[www.centrasemi.com](http://www.centrasemi.com)

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[www.centrasemi.com/wwreps](http://www.centrasemi.com/wwreps)

**Worldwide Distributors:**  
[www.centrasemi.com/wwdistributors](http://www.centrasemi.com/wwdistributors)

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